

What is claimed is:

1. A near infrared-cutting material produced by forming, on a transparent substrate, a transparent resin film containing at least a near infrared absorbing-dye and a dye having a maximum absorption wavelength at 550 to 620 nm, wherein the amount of the solvent remaining in the transparent resin film is 5 ppm by weight to less than 500 ppm by weight.

2. A near infrared-cutting material produced by forming, on a transparent substrate, a transparent resin film containing at least a near infrared absorbing-dye and a transparent resin adhesive layer containing at least a dye having a maximum absorption wavelength at 550 to 620 nm so that the transparent resin adhesive layer becomes the outermost layer, wherein the amount of the solvent remaining in the transparent resin film and/or the transparent resin adhesive layer is 5 ppm by weight to less than 500 ppm by weight.

3. A near infrared-cutting material according to Claim 1 or 2, wherein the resin for the transparent resin

film is a polycarbonate and/or a polyarylate.

4. A near infrared-cutting material according to Claim 1 or 2, wherein the near infrared-absorbing dye is a dithiol-metal complex compound and/or a diimonium compound.

5. A near infrared-cutting material according to Claim 1 or 2, wherein the dye having a maximum absorption wavelength at 550 to 620 nm is a cyanine compound.

6. A process for producing a near infrared-cutting material, which comprises coating, on a transparent substrate, a transparent resin solution containing at least a near infrared absorbing-dye and a dye having a maximum absorption wavelength at 550 to 620 nm, drying the resulting material at atmospheric pressure until the amount of the solvent remaining in the formed resin film becomes 3% by weight or less, and then drying the resulting material under reduced pressure until the amount of the solvent in the film becomes 5 ppm by weight to less than 500 ppm by weight.

7. A process for producing a near infrared-

cutting material according to Claim 6, wherein the pressure employed during the drying under reduced pressure is 10^{-5} to 10^4 Pa and the temperature employed during the drying under reduced pressure is 5 to 150°C lower than
5 the temperature employed during the drying at atmospheric pressure.

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